

SOT193-2

plastic single in-line power package; 13 leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	SIL13P
Package type industry code	SIL13P
Package style descriptive code	BCC (bottom chip carrier)
Package style suffix code	P (power)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	23.6	-	23.8	24	mm
E	package width	11.8	-	12	12.2	mm
A ₂	package height	4.4	-	4.5	4.6	mm
n ₂	actual quantity of termination	-	-	13	-	



2. Package outline

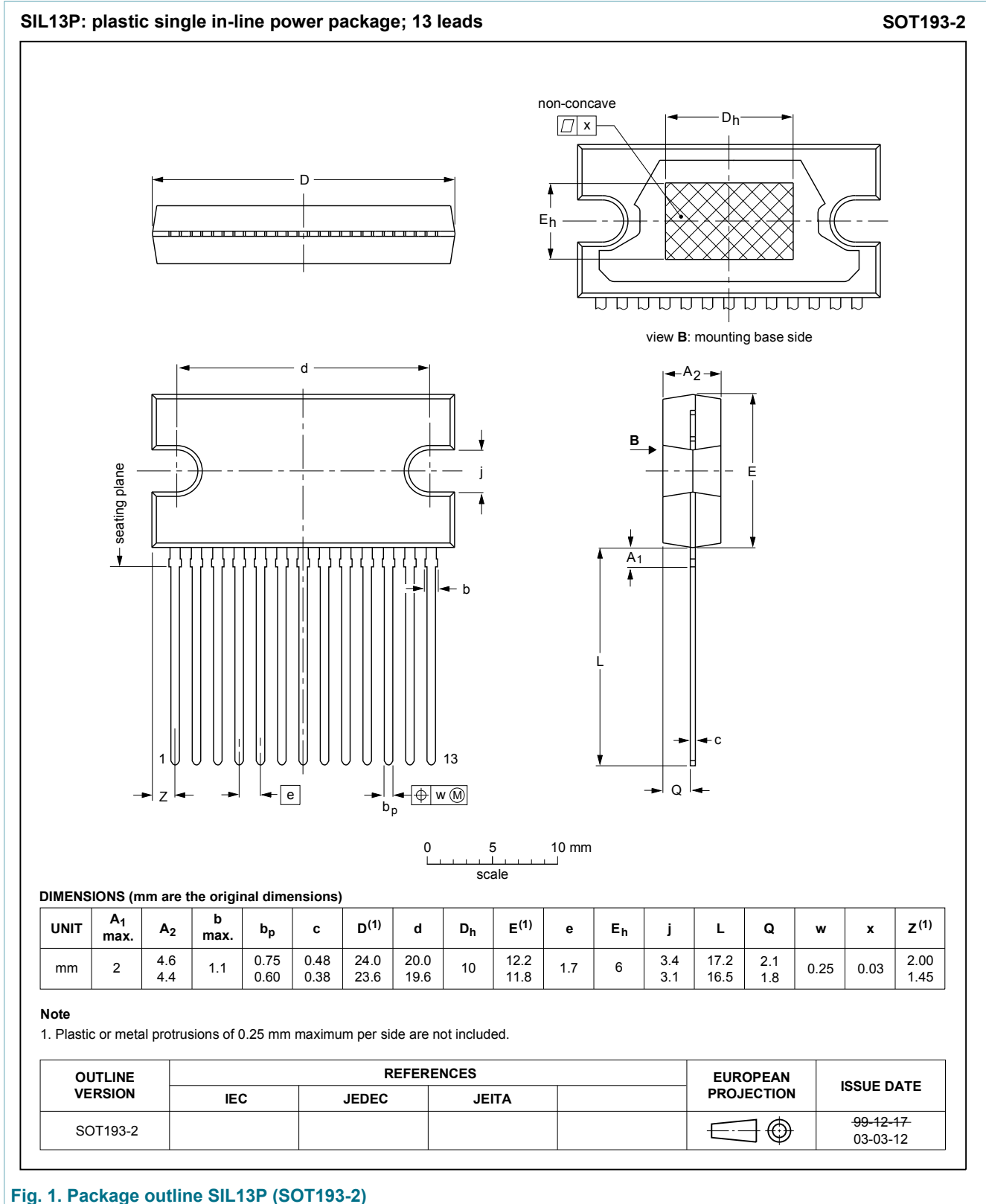


Fig. 1. Package outline SIL13P (SOT193-2)

3. Legal information

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